

LNJ024X4ARA1

High Bright Surface Mounting Chip LED

3528 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation | P_D | 120 | mW |
| Forward current | I_F | 30 | mA |
| Pulse forward current * | I_{FP} | 70 | mA |
| Reverse voltage | V_R | 5 | V |
| Operating ambient temperature | T_{opr} | -40 to +100 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -40 to +100 | $^\circ\text{C}$ |

■ Lighting Color

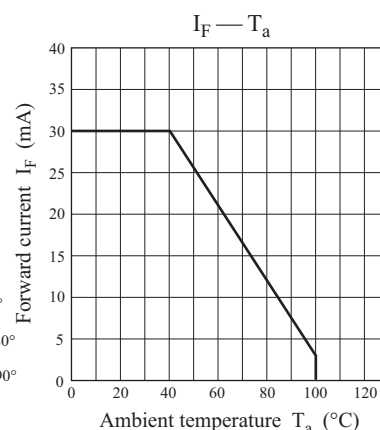
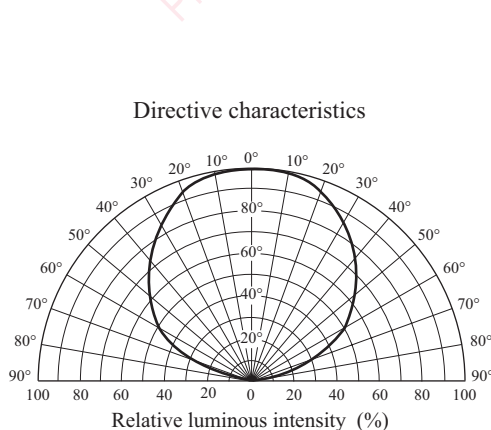
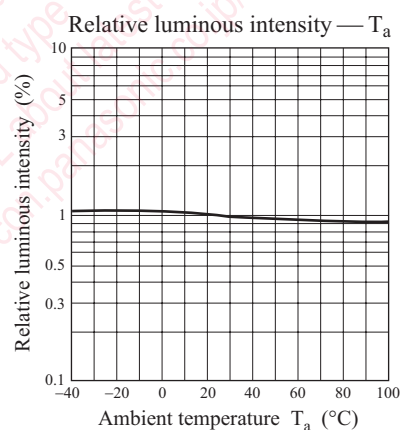
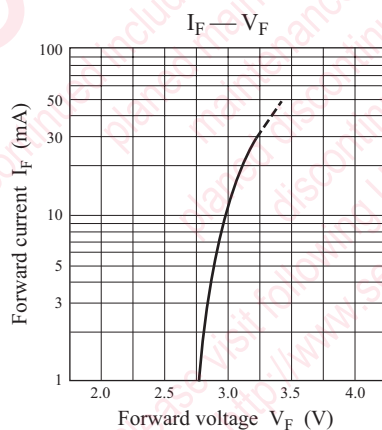
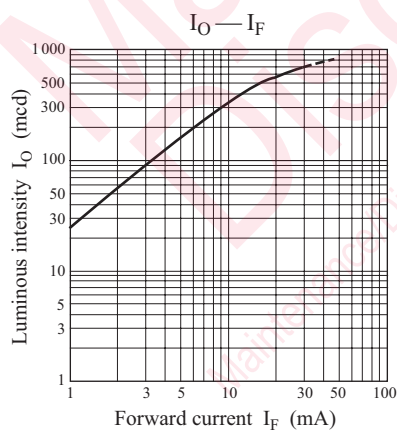
- White

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

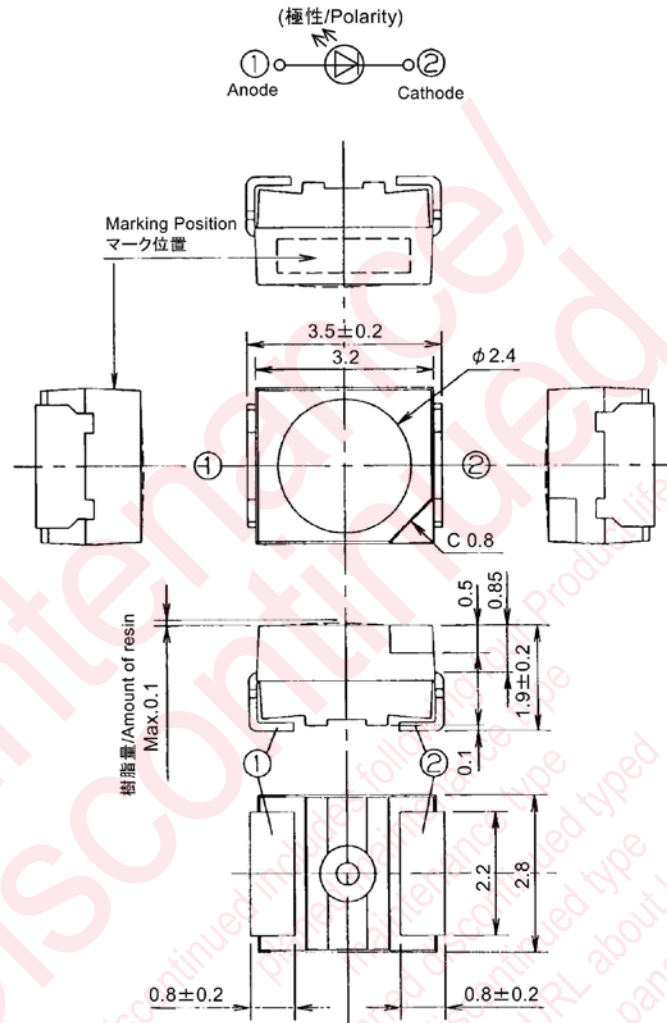
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--------------------------|--------|----------------------|-----|-------|-----|---------------|
| Luminous intensity * | I_O | $I_F = 20\text{ mA}$ | 380 | 600 | 940 | mcd |
| Reverse current | I_R | $V_R = 5\text{ V}$ | | | 100 | μA |
| Forward voltage | V_F | $I_F = 20\text{ mA}$ | | 3.1 | 3.8 | V |
| Chromaticity coordinates | x | $I_F = 20\text{ mA}$ | | 0.300 | | — |
| | y | $I_F = 20\text{ mA}$ | | 0.300 | | — |

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

LLDFTR4J2400



- Pin name
- 1: Anode
- 2: Cathode

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